SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

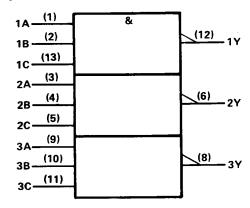
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7410, SN74LS10, and SN74S10 are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE (each gate)

H	NPUT	s	OUTPUT
A	В	С	Y
н	Н	н	Ł
L	X	×	н
X	L	×	н
X	Х	L	н
^	^	٦,	• • •

logic symbol†



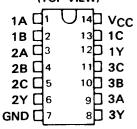
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

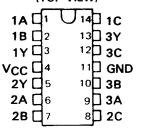
positive logic

$$Y = \overline{A \cdot B \cdot C}$$
 or $Y = \overline{A} + \overline{B} + \overline{C}$

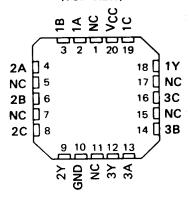
SN5410 . . . J PACKAGE SN54LS10, SN54S10 . . . J OR W PACKAGE SN7410 . . . N PACKAGE SN74LS10, SN74S10 . . . D OR N PACKAGE (TOP VIEW)



SN5410 . . . W PACKAGE (TOP VIEW)

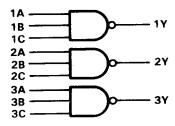


SN54LS10, SN54S10 . . . FK PACKAGE (TOP VIEW)



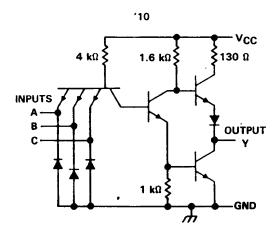
NC - No internal connection

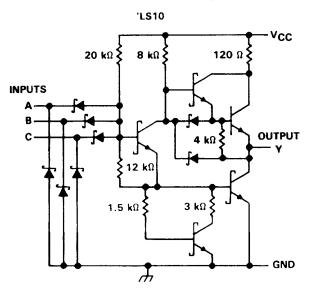
logic diagram (positive logic)

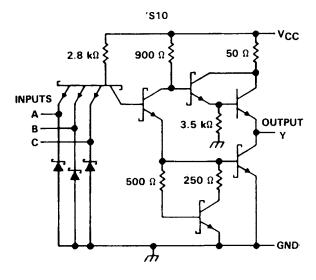




schematics (each gate)







Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '10, 'S10	5.5 V
'LS10	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

		SN5410			SN7410			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V _{IH} High-level input voltage	2			2			V	
VIL Low-level input voltage			0.8			0.8	V	
IOH High-level output current			- 0.4			- 0.4	mA	
IOL Low-level output current			16			16	mA	
TA Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T			SN541)		SN741	0		
						MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
11	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ΉΗ	V _{CC} = MAX,	V ₁ = 2.4 V				40			40	μА
IL	V _{CC} = MAX,	V ₁ = 0.4 V			-	- 1.6			- 1.6	mA
¹os§	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
Iссн	V _{CC} = MAX,	V1 = 0 V			3	6		3	6	mA
¹ CCL	V _{CC} = MAX,	V ₁ = 4.5 V			9	16.5		9	16.5	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

242445750	FROM	то					
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A, B or C				11	22	ns
^t PHL	A, B 01 C	Ť	$R_L = 400 \Omega$, $C_L = 15 p$	F	7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time.

SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN54LS10			SN74LS10		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	v
V _{IH} High-level input voltage	2			2			V
VIL Low-level input voltage			0.7			8.0	V
IOH High-level output current			- 0.4			- 0.4	mA
IOL Low-level output current			4			8	mA
T _A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54LS	10	İ	SN74LS	S10 ·	
FARAMETER				TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN, I _I = - 18	mA			- 1.5			- 1.5	٧
V _{ОН}	V _{CC} = MIN, V _{IL} = MA	AX, I _{OH} = -0.4 mA	2.5	3.4		2.7	3.4		٧
V	V _{CC} = MIN, V _{IH} = 2 \	V, I _{OL} = 4 mA		0.25	0.4			0.4	
VOL	V _{CC} = MIN, V _{IH} = 2 \	V, I _{OL} = 8 mA					0.25	0.5	\ \
l ₁	V _{CC} = MAX, V _I = 7 V				0.1			0.1	mA
ЧН	V _{CC} = MAX, V _I = 2.7 V	V			20			20	μΑ
IιΓ	V _{CC} = MAX, V ₁ = 0.4	V		-	- 0.4			- 0.4	mA
los§	V _{CC} = MAX		- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX, V _I = 0 V			0.6	1.2		0.6	1.2	mΑ
ICCL	V _{CC} = MAX, V ₁ = 4.5 V	V		1.8	3.3		1.8	3.3	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	A, B or C	Y	$R_1 = 2 k\Omega$, $C_1 = 15 pF$		9	15	ns
^t PHL		·			10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

			SN54S10			SN74S10		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	٧
ЮН	High-level output current			– 1			- 1	mA
loL	Low-level output current		·	20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEGT COMPLETIONS T			SN54S1	0		SN74S	10	UNIT	
FANAIVIETEN		TEST CONDITIONS †				MAX	MIN	TYP‡	MAX	UNIT
v _{IK}	V _{CC} = MIN,	I _I = -18 mA				-1.2			-1.2	٧
V _{OH}	V _{CC} ≈ MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		٧
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 20 mA			0.5			0.5	V
l _l	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
IIH	V _{CC} = MAX,	V _I = 2.7 V				50			50	μА
†IL	V _{CC} = MAX,	V _I = 0.5 V				–2			-2	mA
IOS§	V _{CC} = MAX			-40		-100	-40	·	-100	mA
Iссн	V _{CC} = MAX,	V _I = 0 V			7.5	12		7.5	12	mA
¹ CCL	V _{CC} = MAX,	V _I = 4.5 V	,		15	27		15	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONE	DITIONS	MIN	TYP	MAX	UNIT
^t PLH			R _L = 280 Ω,	C ₁ = 15 pF		3	4.5	ns
^t PHĿ	A D . O	V	NL - 200 12,	CL - 19 PF		3	5	ns
^t PLH	A, B or C	Y	D 200 O	C = 50 = 5		4.5		ns
^t PHL			R _L = 280 Ω,	CL = 50 pF		5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
JM38510/00103BCA	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
JM38510/00103BDA	OBSOLETE	CFP	W	14		None	Call TI	Call TI
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/07005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SN54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN7410N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7410N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74S10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SNJ5410W	OBSOLETE	CFP	W	14		None	Call TI	Call TI
SNJ5410WA	OBSOLETE	CFP	WA	14		None	Call TI	Call TI
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM

28-Feb-2005

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

Copyright © Each Manufacturing Company.

All Datasheets cannot be modified without permission.

This datasheet has been download from:

www.AllDataSheet.com

100% Free DataSheet Search Site.

Free Download.

No Register.

Fast Search System.

www.AllDataSheet.com